IN74AC299

8-Bit Bidirectional Universal Shift Register with Parallel I/O High-Speed Silicon-Gate CMOS

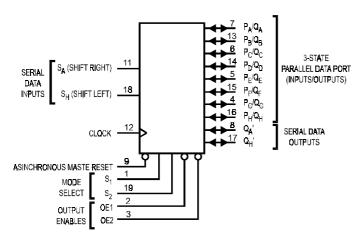
The IN74AC299 is identical in pinout to the LS/ALS299, HC/HCT299. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LS/ALS outputs.

The IN74AC299 features a multiplexed parallel input/output data port to achieve full 8-bit handling in a 20 pin package. Due to the large output drive capability and the 3-state feature, this device is ideally suited for interface with bus lines in a bus-oriented system.

Two Mode-Select inputs and two Output Enable inputs are used to choose the mode of operation as listed in the Function Table. Synchronous parallel loading is accomplished by taking both Mode-Select lines, S_1 and S_2 , high. This places the outputs in the high-impedance state, which permits data applied to the data port to be clocked into the register. Reading out of the register can be accomplished when the outputs are enabled. The active-low asynchronous Reset overrides all other inputs.

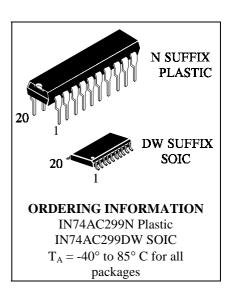
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 to 6.0 V
- Low Input Current: 1.0 μA; 0.1 μA @ 25°C
- High Noise Immunity Characteristic of CMOS Devices
- Outputs Source/Sink 24 mA

LOGIC DIAGRAM

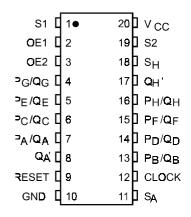


PIN 20=V_{CC}

PIN 10 = GND



PIN ASSIGNMENT





MAXIMUM RATINGS*

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	-0.5 to +7.0	V
V_{IN}	DC Input Voltage (Referenced to GND)	-0.5 to V_{CC} +0.5	V
V _{OUT}	DC Output Voltage (Referenced to GND)	-0.5 to V_{CC} +0.5	V
I_{IN}	DC Input Current, per Pin	±20	mA
I_{OUT}	DC Output Sink/Source Current, per Pin	±50	mA
I_{CC}	DC Supply Current, V _{CC} and GND Pins	±50	mA
P_{D}	Power Dissipation in Still Air, Plastic DIP+ SOIC Package+	750 500	mW
Tstg	Storage Temperature	-65 to +150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (Plastic DIP or SOIC Package)	260	°C

^{*}Maximum Ratings are those values beyond which damage to the device may occur. Functional operation should be restricted to the Recommended Operating Conditions.

SOIC Package: : - 7 mW/ $^{\circ}$ C from 65 $^{\circ}$ to 125 $^{\circ}$ C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V
V_{IN}, V_{OUT}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V
T_{J}	Junction Temperature (PDIP)		140	°C
T_A	Operating Temperature, All Package Types	-40	+85	°C
I_{OH}	Output Current - High		-24	mA
I_{OL}	Output Current - Low		24	mA
t _r , t _f	Input Rise and Fall Time * $V_{CC} = 3.0 \text{ V}$ (except Schmitt Inputs) $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 5.5 \text{ V}$	0 0 0	150 40 25	ns/V

 $[\]overline{^*V_{IN}}$ from 30% to 70% V_{CC}

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{IN} and V_{OUT} should be constrained to the range $GND \leq (V_{IN} \text{ or } V_{OUT}) \leq V_{CC}$.

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.



⁺Derating - Plastic DIP: - 10 mW/°C from 65° to 125°C

DC ELECTRICAL CHARACTERISTICS(Voltages Referenced to GND)

			V_{CC}	Guarant	eed Limits	
Symbol	Parameter	Test Conditions	V	25 °C	-40°C to 85°C	Unit
V_{IH}	Minimum High-Level Input Voltage	V _{OUT} =0.1 V or V _{CC} -0.1 V	3.0 4.5 5.5	2.1 3.15 3.85	2.1 3.15 3.85	V
V_{IL}	Maximum Low - Level Input Voltage	V _{OUT} =0.1 V or V _{CC} -0.1 V	3.0 4.5 5.5	0.9 1.35 1.65	0.9 1.35 1.65	V
V_{OH}	Minimum High-Level Output Voltage	I _{OUT} ≤ -50 μA	3.0 4.5 5.5	2.9 4.4 5.4	2.9 4.4 5.4	V
		$^*V_{IN}$ = V_{IH} or V_{IL} I_{OH} =-12 mA I_{OH} =-24 mA I_{OH} =-24 mA	3.0 4.5 5.5	2.56 3.86 4.86	2.46 3.76 4.76	
V_{OL}	Maximum Low-Level Output Voltage	-001 = 0 0 Pm -			0.1 0.1 0.1	V
		$^*V_{IN} = V_{IH}$ or V_{IL} $I_{OL} = 12$ mA $I_{OL} = 24$ mA $I_{OL} = 24$ mA	3.0 4.5 5.5	0.36 0.36 0.36	0.44 0.44 0.44	
I_{IN}	Maximum Input Leakage Current	V _{IN} =V _{CC} or GND	5.5	±0.1	±1.0	μΑ
I_{OZ}	Maximum Three- State Leakage Current	$\begin{aligned} &V_{IN}\left(OE\right) = V_{IH} \text{ or } V_{IL} \\ &V_{IN} = V_{CC} \text{ or GND} \\ &V_{OUT} = V_{CC} \text{ or GND} \end{aligned}$	5.5	±0.6	±6.0	μА
I_{OLD}	+Minimum Dynamic Output Current	V _{OLD} =1.65 V Max	5.5		75	mA
I_{OHD}	+Minimum Dynamic Output Current	V _{OHD} =3.85 V Min	5.5		-75	mA
I_{CC}	Maximum Quiescent Supply Current (per Package)	V _{IN} =V _{CC} or GND	5.5	8.0	80	μА

^{*} All outputs loaded; thresholds on input associated with output under test.

Note: I_{IN} and I_{CC} @ 3.0 V are guaranteed to be less than or equal to the respective limit @ 5.5 V V_{CC}



⁺Maximum test duration 2.0 ms, one output loaded at a time.

$\textbf{AC ELECTRICAL CHARACTERISTICS}(C_L = 50 pF, Input \ t_i = t_f = 3.0 \ ns)$

		V _{CC} *	(Guarantee	ed Limits					
Symbol	Parameter	V	25 °C		-40° 85°	Unit				
			Min	Max	Min	Max				
f_{max}	Maximum Clock Frequency (Figure 1)	3.3 5.0	90 130		80 105		MHz			
t _{PLH}	Propagation Delay, Clock to Q _A ' or Q _H ' (Figure 1)	3.3 5.0	8.5 5.5	20.5 14.0	7.0 4.5	22.0 15.0	ns			
t _{PHL}	Propagation Delay, Clock to Q _A ' or Q _H ' (Figure 1)	3.3 5.0	8.5 5.5	21.5 14.5	7.0 5.0	23.0 16.0	ns			
t _{PLH}	Propagation Delay, Clock to Q _A thru Q _H (Figure 1)	3.3 5.0	9.0 6.0	20.5 14.5	7.5 5.0	22.5 16.0	ns			
t _{PHL}	Propagation Delay, Clock to Q _A thru Q _H (Figure 1)	3.3 5.0	10.0 6.5	23.0 16.0	8.5 6.0	24.5 17.5	ns			
t _{PHL}	Propagation Delay, Reset to Q _A ' or Q _H ' (Figure 2)	3.3 5.0	9.0 5.5	22.5 15.5	7.5 5.0	25.0 17.0	ns			
t _{PHL}	Propagation Delay, Reset to Q _A thru Q _H (Figure 2)	3.3 5.0	9.0 5.5	21.5 15.0	7.5 5.0	24.0 16.5	ns			
t _{PZH}	Propagation Delay , OE1, OE2 to Q_A thru Q_H (Figure 3)	3.3 5.0	7.0 4.5	18.0 12.5	6.0 4.0	19.5 13.5	ns			
t _{PZL}	Propagation Delay , OE1, OE2 to Q_A thru Q_H (Figure 3)	3.3 5.0	7.0 5.0	18.0 12.5	6.0 4.0	20.5 14.0	ns			
t _{PHZ}	Propagation Delay , OE1, OE2 to Q_A thru Q_H (Figure 3)	3.3 5.0	6.5 3.5	18.5 14.0	5.5 3.0	19.5 15.0	ns			
t_{PLZ}	Propagation Delay , OE1, OE2 to Q_A thru Q_H (Figure 3)	3.3 5.0	5.5 3.5	17.0 12.5	4.5 2.0	19.0 13.5	ns			
C_{IN}	Maximum Input Capacitance	5.0	4	4.5 4.5			pF			

		Typical @25°C,V _{CC} =5.0 V			
C_{PD}	Power Dissipation Capacitance	170	pF		

*Voltage Range 3.3 V is 3.3 V ± 0.3 V Voltage Range 5.0 V is 5.0 V ± 0.5 V



TIMING REQUIREMENTS(C_L =50pF,Input t_r = t_f =3.0 ns)

		$V_{CC}^{^*}$	Guarantee		
Symbol	Parameter	V	25 °C	-40°C to 85°C	Unit
t_{su}	Minimum Setup Time, Mode Select S1 or S2 to Clock (Figure 4)	3.3 5.0	8.0 5.0	8.5 5.5	ns
t_{su}	Minimum Setup Time, Data Inputs P _A thru P _H to Clock (Figure 4)	3.3 5.0	5.5 3.5	6.0 4.0	ns
t_{su}	Minimum Setup Time, Data Inputs S _A , S _H to Clock (Figure 4)	3.3 5.0	6.5 4.0	7.0 4.5	ns
t _h	Minimum Hold Time, Clock to Mode Select S1 or S2 (Figure 4)	3.3 5.0	0.5 1.0	0.5 1.0	ns
t_h	$\begin{array}{c} \mbox{Minimum Hold Time, Clock to Data Inputs } P_{A} \\ \mbox{thru } P_{H} \mbox{ (Figure 4)} \end{array}$	3.3 5.0	0 1.0	0 1.0	ns
t _h	Minimum Hold Time, Clock to Data Inputs S _A , S _H (Figure 4)	3.3 5.0	0 1.0	0.5 1.0	ns
t_{rec}	Minimum Recovery Time, Reset Inactive to Clock (Figure 2)	3.3 5.0	1.5 1.5	1.5 1.5	ns
$t_{\rm w}$	Minimum Pulse Width, Clock (Figure 1)	3.3 5.0	4.5 3.5	5.0 3.5	ns
$t_{\rm w}$	Minimum Pulse Width, Reset (Figure 2)	3.3 5.0	4.5 3.5	5.0 3.5	ns

^{*}Voltage Range 3.3 V is 3.3 V ± 0.3 V Voltage Range 5.0 V is 5.0 V ± 0.5 V



FUNCTION TABLE

Inputs										Response								
Mode	Reset		ode ect		tput bles	Clock		rial outs	P _A / Q _A		P _C / Q _C	$\begin{array}{c} P_D / \\ Q_D \end{array}$	P _E / Q _E	P _F /Q _F	$\begin{array}{c} P_G / \\ Q_G \end{array}$	P _H / Q _H	Q _A '	Q _H '
		S_2	S_1	OE1 [♠]	OE2 [♠]		D_A	D_{H}										
Reset	L	X	L	L	L	X	X	X	L	L	L	L	L	L	L	L	L	L
	L	L	X	L	L	X	X	X	L	L	L	L	L	L	L	L	L	L
	L	Н	Н	X	X	X	X	X			Q_{A}	throu	ıgh Q	$Q_H=Z$			L	L
Shift Right	Н	L	Н	Н	X	\	D	X	5		_		thro F _A →	_		Z;	D	Q_{G}
	Н	L	Н	X	Н	\	D	X Shift Right: Q_A through $Q_H=Z$ $D_A ightharpoonup F_A$; $F_A ightharpoonup F_B$; etc					Z;	D	Q_{G}			
	Н	L	Н	L	L	\	D	X	Shift Right: $D_A \rightarrow F_A = Q_A$; $F_A \rightarrow F_B = Q_B$; etc						D	Q_{G}		
Shift Left	Н	Н	L	Н	X	_	X	D					throu F _H →	_	~	Z ;	Q _B	D
	Н	Н	L	X	Н	\	X	D	Shift Left: Q_A through $Q_H=Z$; $D_H \longrightarrow F_H$; $F_H \longrightarrow F_G$; etc					Z ;	Q _B	D		
	Н	Н	L	L	L	\	X	D	Shift Left: $D_H \longrightarrow F_H = Q_H$; $F_H \longrightarrow F_G = Q_G$; etc						Q_{B}	D		
Parallel Load	Н	Н	Н	X	X	\	X	X	Parallel Load: $P_N \longrightarrow F_N$						P _A	P_{H}		
Hold	Н	L	L	Н	X	X	X	X	Н	Hold: Q _A through Q _H =Z; F _N =F _N						P_{A}	P_{H}	
	Н	L	L	X	Н	X	X	X	Н	Iold:	$Q_A t$	hrou	gh Q _l	H=Z;	$F_N=1$	F_N	P_{A}	P_{H}
	Н	L	L	L	L	X	X	X			Н	old:	$Q_N =$	Q _H			P_{A}	P_{H}

Z = high impedance

D = data on serial input

F = flip-flop (see Logic Diagram)

When one or both output controls are high the eight input/output terminals are disabled to the high-impedance state; however, sequential operation or clearing of the register is not affected.

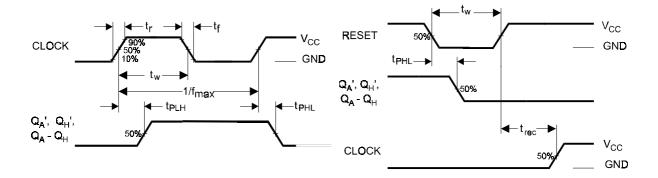


Figure 1. Switching Waveform

Figure 2. Switching Waveform

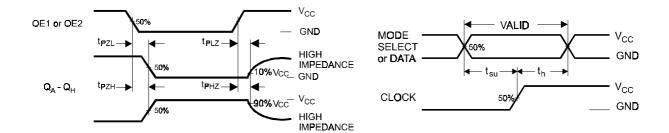


Figure 3. Switching Waveform

Figure 4. Switching Waveform



EXPANDED LOGIC DIAGRAM

